

AS1744, AS1745

Data Sheet

High-Speed, Low-Voltage, Dual, Single-Supply, 4Ω, SPDT Analog Switches

1 General Description

The AS1744/AS1745 are high-speed, low-voltage, dual single-pole/double-throw (SPDT) analog switches.

Fast switching speeds, low ON-resistance, and low power-consumption make these devices ideal for single-cell battery powered applications.

These highly-reliable devices operate from a +1.8 to +5.5V supply, are differentiated by inverted logic, and support break-before-make switching.

With low ON-resistance (R_{ON}), R_{ON} matching, and R_{ON} flatness, the devices can accurately switch signals for sample and hold circuits, digital filters, and op-amp gain switching networks.

The devices are available in a 10-pin MSOP package and a 10-pin TDFN package.

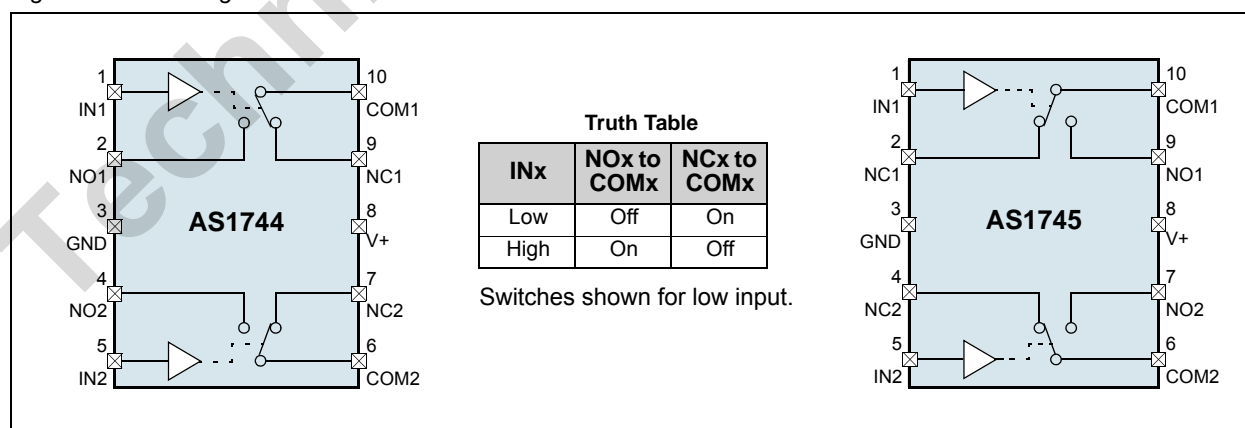
2 Key Features

- ON-Resistance:
 - 4Ω (+5V supply)
 - 5.5Ω (+3V supply)
- R_{ON} Matching: 0.2Ω (+5V supply)
- R_{ON} Flatness: 1Ω (+5V supply)
- Supply Voltage Range: +1.8 to +5.5V
- 1.8V Operation:
 - 9.5Ω ON-Resistance over Temperature
 - 38ns Turn On Time
 - 12ns Turn Off Time
- Current-Handling: 100mA Continuous
- Break-Before-Make Switching
- Rail-to-Rail Signal Handling
- Crosstalk: -90dB at 1MHz
- Off-Isolation: -85dB at 1MHz
- Total Harmonic Distortion: 0.1%
- Operating Temperature Range: -40 to +85°C
- Package Types:
 - 10-pin MSOP
 - 10-pin TDFN

3 Applications

The devices are ideal for use in power routing systems, cordless and mobile phones, MP3 players, CD and DVD players, PDAs, handheld computers, digital cameras, and any other application where high-speed signal switching is required.

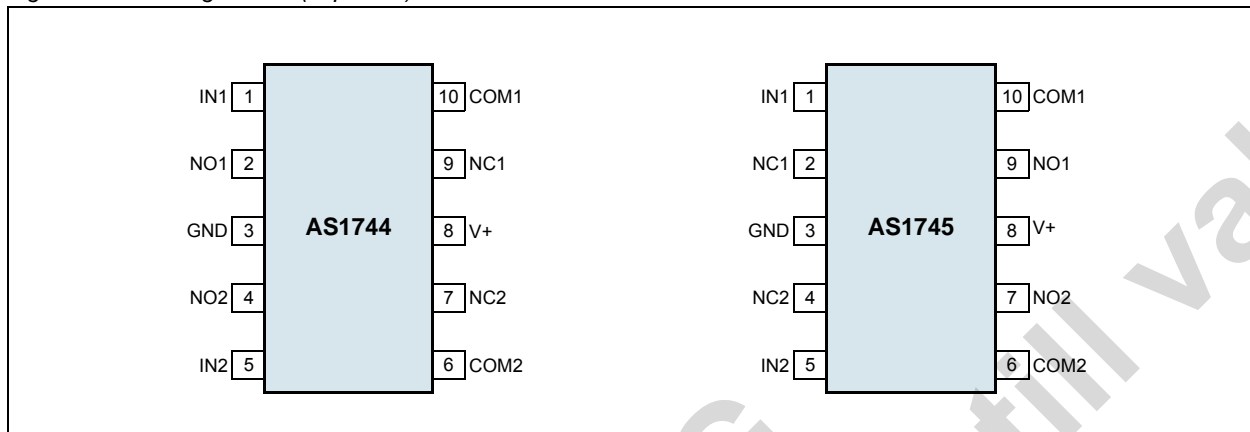
Figure 1. Block Diagrams



4 Pinout

Pin Assignments

Figure 2. Pin Assignments (Top View)



Pin Descriptions

Table 1. Pin Descriptions

Pin Number		Pin Name	Description
AS1744	AS1745		
10	10	COM1	Analog Switch 1 Common
6	6	COM2	Analog Switch 2 Common
3	3	GND	Ground
1	1	IN1	Analog Switch 1 Logic Control Input
5	5	IN2	Analog Switch 2 Logic Control Input
9	2	NC1	Analog Switch 1 Normally Closed Terminal
7	4	NC2	Analog Switch 2 Normally Closed Terminal
2	9	NO1	Analog Switch 1 Normally Open Terminal
4	7	NO2	Analog Switch 2 Normally Open Terminal
8	8	V+	Input Supply Voltage. +1.8 to +5.5V

5 Absolute Maximum Ratings

Stresses beyond those listed in [Table 2](#) may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Section 6 Electrical Characteristics on page 4 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 2. Absolute Maximum Ratings

Parameter	Min	Max	Units	Comments
V+, IN1, IN2 to GND	-0.3	+7	V	
COMx, NOx, NCx to GND [†]	-0.3	V+ + 0.3	V	
COMx, NOx, NCx Continuous Current	-100	+100	mA	
COMx, NOx, NCx Peak Current	-150	+150	mA	Pulsed at 1ms, 10% duty cycle
Continuous Power Dissipation (T _{AMB} = +70°C)		330	mW	Derate at 4.7mW/°C above +70°C
Electro-Static Discharge		1000	V	HBM Mil-Std883E 3015.7 methods
Latch Up Immunity		100	mA	Norm: JEDEC 17
Operating Temperature Range	-40	+85	°C	
Junction Temperature		150	°C	
Storage Temperature Range	-65	+150	°C	
Package Body Temperature		+260	°C	The reflow peak soldering temperature (body temperature) specified is in accordance with IPC/JEDEC J-STD-020C "Moisture/Reflow Sensitivity Classification for Non-Hermetic Solid State Surface Mount Devices"

[†] Signals on pins COM1, COM2, NO1, NO2, NC1, or NC2 that exceed V+ or GND are clamped by internal diodes. Limit forward-diode current to the maximum current rating.

6 Electrical Characteristics

$V_+ = +4.5$ to 5.5 V, $V_{IH} = +2.4$ V, $V_{IL} = +0.8$ V, $T_{AMB} = T_{MIN}$ to T_{MAX} (unless otherwise specified). Typ Values @ $T_{AMB} = +25^\circ\text{C}$.

Table 3. +5V Supply Electrical Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Analog Switch							
V _{COMx} , V _{NOx} , V _{NCx}	Analog Signal Range			0		V+	V
R _{ON}	ON-Resistance	V+ = 4.5V, I _{COMx} = 10mA, V _{NOx} or V _{NCx} = 0 to V+	T _{AMB} = +25°C T _{AMB} = T _{MIN} to T _{MAX}		2.5	4 4.5	Ω
ΔR _{ON}	ON-Resistance Match Between Channels ¹	V+ = 4.5V, I _{COMx} = 10mA, V _{NOx} or V _{NCx} = 0 to V+	T _{AMB} = +25°C T _{AMB} = T _{MIN} to T _{MAX}		0.1	0.2 0.4	Ω
R _{FLAT(ON)}	ON-Resistance Flatness ²	V+ = 4.5V, I _{COMx} = 10mA, V _{NOx} or V _{NCx} = 0 to V+	T _{AMB} = +25°C T _{AMB} = T _{MIN} to T _{MAX}		0.5	1 1.2	Ω
I _{NOx(OFF)} , I _{NCx(OFF)}	NOx or NCx Off-Leakage Current ³	V+ = 5.5V, V _{COMx} = 1 or 4.5V, V _{NOx} or V _{NCx} = 4.5 or 1V	T _{AMB} = +25°C T _{AMB} = T _{MIN} to T _{MAX}	-0.1 -0.3	±0.01	0.1 0.3	nA
I _{COMx(OFF)}	COMx Off-Leakage Current ³	V+ = 5.5V, V _{COMx} = 1 or 4.5V, V _{NOx} or V _{NCx} = 4.5 or 1V	T _{AMB} = +25°C T _{AMB} = T _{MIN} to T _{MAX}	-0.1 -3	±0.01	0.1 3	nA
I _{COMx(ON)}	COMx On-Leakage Current ³	V+ = 5.5V, V _{COMx} = 4.5 or 1V, V _{NOx} or V _{NCx} = 4.5 or 1V	T _{AMB} = +25°C T _{AMB} = T _{MIN} to T _{MAX}	-0.4 -4	±0.1	0.4 4	nA
Logic Input: INx							
V _{IH}	Input Logic High			2.4			V
V _{IL}	Input Logic Low					0.8	V
I _{IH} , I _{IL}	Input Leakage Current	V _{INx} = 0 or +5.5V		-100	5	100	nA
Switch Dynamic Characteristics							
t _{ON}	Turn On Time ³	V _{NOx} or V _{NCx} = 3V, R _{LOAD} = 300Ω, C _{LOAD} = 35pF, Figure 12	T _{AMB} = +25°C T _{AMB} = T _{MIN} to T _{MAX}		14	17 18	ns
t _{OFF}	Turn Off Time ³	V _{NOx} or V _{NCx} = 3V, R _{LOAD} = 300Ω, C _{LOAD} = 35pF, Figure 12	T _{AMB} = +25°C T _{AMB} = T _{MIN} to T _{MAX}		4	6 8	ns
t _{BBM}	Break-Before-Make ³	V _{NOx} or V _{NCx} = 3V, R _{LOAD} = 300Ω, C _{LOAD} = 35pF, Figure 13	T _{AMB} = +25°C T _{AMB} = T _{MIN} to T _{MAX}		10		ns
Q	Charge Injection	V _{GEN} = 2V, R _{GEN} = 0, C _{LOAD} = 1.0nF, Figure 14			7		pC
C _{NOx(OFF)} , C _{NCx(OFF)}	NOx, NCx Off-Capacitance	V _{NOx} or V _{NCx} = GND, f = 1MHz, Figure 15			20		pF
C _{COMx(ON)}	COMx On-Capacitance	V _{COMx} = GND, f = 1MHz, Figure 15			56		pF
V _{ISO}	Off-Isolation ⁴	f = 10MHz, R _{LOAD} = 50Ω, C _{LOAD} = 5pF, Figure 16 f = 1MHz, R _{LOAD} = 50Ω, C _{LOAD} = 5pF, Figure 16			-52 -85		dB
V _{CT}	Crosstalk ⁵	f = 10MHz, R _{LOAD} = 50Ω, C _{LOAD} = 5pF, Figure 16 f = 1MHz, R _{LOAD} = 50Ω, C _{LOAD} = 5pF, Figure 16			-52 -90		dB
THD	Total Harmonic Distortion	f = 20Hz to 20kHz, V _{NOx} = 5Vp-p, R _{LOAD} = 600Ω			0.1		%
Power Supply							
I+	Positive Supply Current	V+ = 5.5V, V _{INx} = 0 or V+			0.01	1.0	μA

$V_+ = +2.7$ to $3.6V$, $V_{IH} = +2.0V$, $V_{IL} = +0.4V$, $T_{AMB} = T_{MIN}$ to T_{MAX} (unless otherwise specified). Typ values @ $T_{AMB} = +25^\circ C$.

Table 4. +3V Supply Electrical Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Analog Switch							
V_{COMx} , V_{NOx} , V_{NCx}	Analog Signal Range			0		V+	V
R_{ON}	ON-Resistance	$V+ = 2.7V$, $I_{COMx} = 10mA$, V_{NOx} or $V_{NCx} = 0$ to $V+$	$T_{AMB} = +25^{\circ}C$		5	5.5	Ω
			$T_{AMB} = T_{MIN}$ to T_{MAX}			8	
ΔR_{ON}	ON-Resistance Match Between Channels ¹	$V+ = 2.7V$, $I_{COMx} = 10mA$, V_{NOx} or $V_{NCx} = 0$ to $V+$	$T_{AMB} = +25^{\circ}C$		0.1	0.2	Ω
			$T_{AMB} = T_{MIN}$ to T_{MAX}			0.4	
$R_{FLAT(ON)}$	ON-Resistance Flatness ²	$V+ = 2.7V$, $I_{COMx} = 10mA$, V_{NOx} or $V_{NCx} = 0$ to $V+$	$T_{AMB} = +25^{\circ}C$		1.5	2	Ω
			$T_{AMB} = T_{MIN}$ to T_{MAX}			2.5	
$I_{NOx(OFF)}$, $I_{NCx(OFF)}$	NOx or NCx Off-Leakage Current ³	$V+ = 3.3V$, $V_{COMx} = 1$ or $3V$, V_{NOx} or $V_{NCx} = 3$ or $1V$	$T_{AMB} = +25^{\circ}C$	-0.1	± 0.01	0.1	nA
			$T_{AMB} = T_{MIN}$ to T_{MAX}	-0.3		0.3	
$I_{COMx(OFF)}$	COMx Off-Leakage Current ³	$V+ = 3.3V$, $V_{COMx} = 1$ or $3V$, V_{NOx} or $V_{NCx} = 3$ or $1V$	$T_{AMB} = +25^{\circ}C$	-0.1	± 0.01	0.1	nA
			$T_{AMB} = T_{MIN}$ to T_{MAX}	-3		3	
$I_{COMx(ON)}$	COMx On-Leakage Current ³	$V+ = 3.3V$, $V_{COMx} = 1$ or $3V$, V_{NOx} or $V_{NCx} = 1$ or $3V$	$T_{AMB} = +25^{\circ}C$	-0.4	± 0.1	0.4	nA
			$T_{AMB} = T_{MIN}$ to T_{MAX}	-4		4	
Logic Input: (INx)							
V_{IH}	Input Logic High			2.0			V
V_{IL}	Input Logic Low					0.4	V
I_{IH}, I_{IL}	Input Leakage Current	$V_{INx} = 0$ or $+5.5V$		-100	5	100	nA
Switch Dynamic Characteristics							
t_{ON}	Turn On Time ³	V_{NOx} or $V_{NCx} = 2V$, $R_{LOAD} = 300\Omega$, $C_{LOAD} = 35pF$, Figure 12	$T_{AMB} = +25^{\circ}C$		17	23	ns
			$T_{AMB} = T_{MIN}$ to T_{MAX}			28	
t_{OFF}	Turn Off Time ³	V_{NOx} or $V_{NCx} = 2V$, $R_{LOAD} = 300\Omega$, $C_{LOAD} = 35pF$, Figure 12	$T_{AMB} = +25^{\circ}C$		6	8	ns
			$T_{AMB} = T_{MIN}$ to T_{MAX}			10	
t_{BBM}	Break-Before-Make ³	V_{NOx} or $V_{NCx} = 2V$, $R_{LOAD} = 300\Omega$, $C_{LOAD} = 35pF$, Figure 13	$T_{AMB} = +25^{\circ}C$		11		ns
			$T_{AMB} = T_{MIN}$ to T_{MAX}	1			
Q	Charge Injection	$V_{GEN} = 1.5V$, $R_{GEN} = 0$, $C_{LOAD} = 1.0nF$, Figure 14			0		pC
$C_{NOx(OFF)}$, $C_{NCx(OFF)}$	NOx, NCx Off-Capacitance	V_{NOx} or $V_{NCx} = GND$, $f = 1MHz$, Figure 15			20		pF
$C_{COMx(ON)}$	COMx On-Capacitance	$V_{COMx} = GND$, $f = 1MHz$, Figure 15			56		pF
V_{ISO}	Off-Isolation ⁴	$f = 10MHz$, $R_{LOAD} = 50\Omega$, $C_{LOAD} = 5pF$, Figure 16			-52		dB
		$f = 1MHz$, $R_{LOAD} = 50\Omega$, $C_{LOAD} = 5pF$, Figure 16			-85		
V_{CT}	Crosstalk ⁵	$f = 10MHz$, $R_{LOAD} = 50\Omega$, $C_{LOAD} = 5pF$, Figure 16			-52		dB
		$f = 1MHz$, $R_{LOAD} = 50\Omega$, $C_{LOAD} = 5pF$, Figure 16			-90		
Power Supply							
$I+$	Positive Supply Current	$V+ = 3.6V$, $V_{IN} = 0$ or $+3.6V$			0.01	1.0	μA

1. $\Delta R_{ON} = R_{ON(MAX)} - R_{ON(MIN)}$.

2. Flatness is defined as the difference between the maximum and the minimum value of ON-resistance as measured over the specified analog signal ranges.

3. Guaranteed by design.

4. Off-Isolation = $20 \log_{10}(V_{COMx}/V_{NOx})$, V_{COMx} = output, V_{NOx} = input to off switch.

5. Between any two switches.

7 Typical Operating Characteristics

Figure 3. Frequency Response

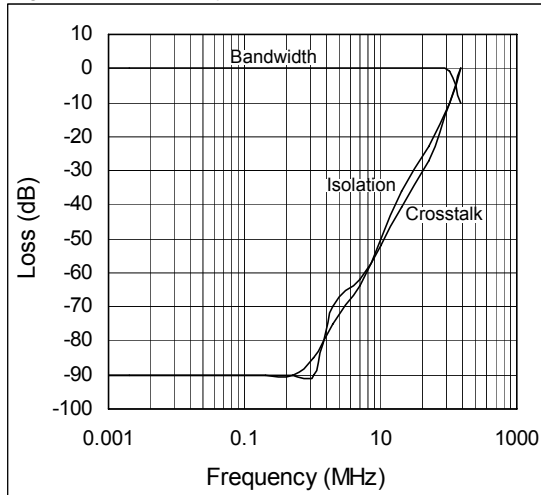


Figure 4. THD vs. Frequency

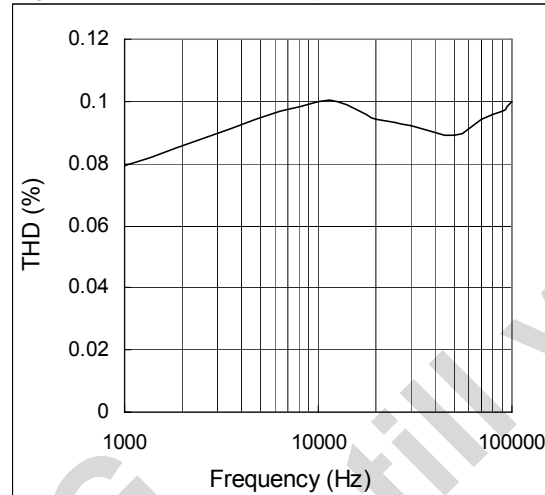


Figure 5. R_{ON} vs. V_{COM} and Temperature ($V_{DD} = 5V$)

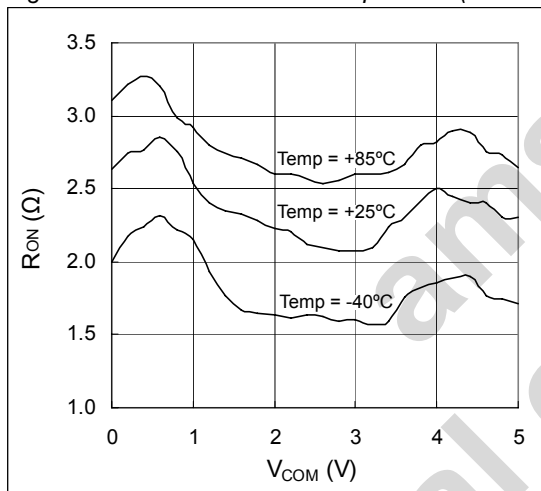


Figure 6. R_{ON} vs. V_{COM} and Temperature ($V_{DD} = 3V$)

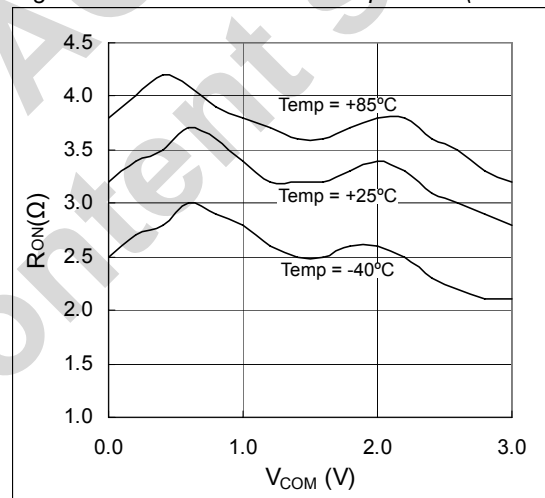


Figure 7. R_{ON} vs. V_{COM}

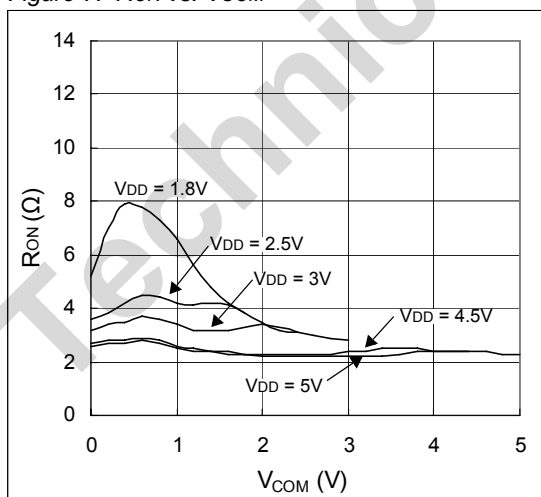


Figure 8. t_{ON}/t_{OFF} vs. Temperature ($V_+ = 5V$)

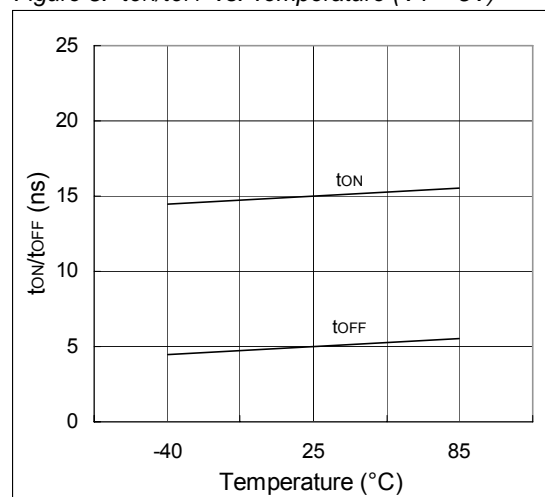


Figure 9. t_{ON}/t_{OFF} vs. Supply Voltage

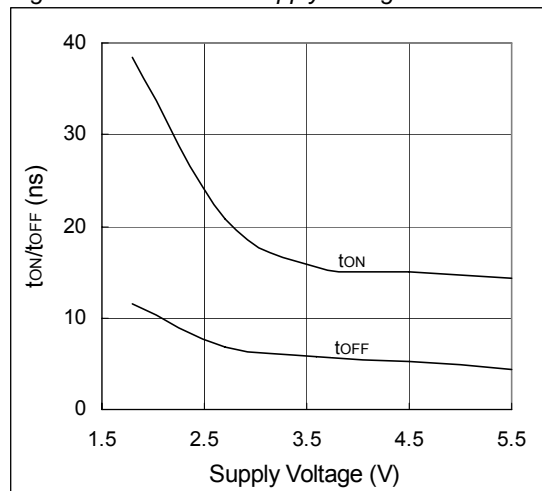
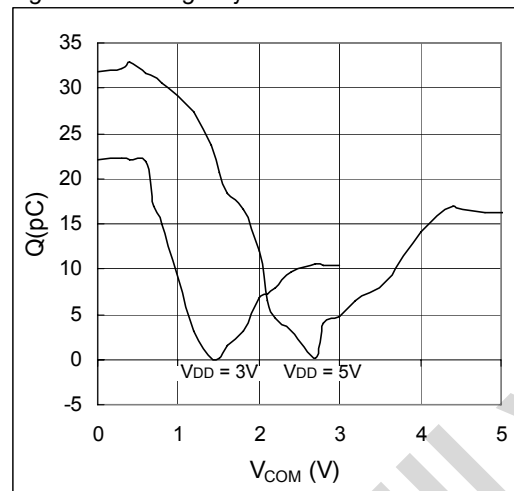


Figure 10. Charge Injection



8 Detailed Description

The AS1744/AS1745 are low ON-resistance, low-voltage, dual analog SPDT switches that operate from a single +1.8 to +5.5V supply.

CMOS process technology allows switching of analog signals that are within the supply voltage range (GND to V+).

ON-Resistance

When powered from a +5V supply, the low R_{ON} (4Ω max) allows high continuous currents to be switched in a wide range of applications. All devices have low R_{ON} flatness (1Ω , max) so they can meet or exceed the low-distortion audio requirements of modern portable audio devices.

Bi-Directional Switching

Pins NOx, NCx, and COMx are bi-directional, thus they can be used as inputs or outputs.

Analog Signal Levels

Analog signals ranging over the entire supply voltage (V+ to GND) can be passed with very little change in ON-resistance (see [Typical Operating Characteristics on page 6](#)).

Logic Inputs

The AS1744/AS1745 logic inputs (INx) can be driven up to +5.5V regardless of the supply voltage value. For example, with a +3.3V supply, IN+ may be driven low to GND and high to +5.5V. This allows the devices to interface with +5V systems using a supply of less than 5V.

9 Application Information

Power-Supply Sequencing

Proper power-supply sequencing is critical for proper operation. The recommended sequence is as follows:

1. V+
2. NOx, NCx, COMx

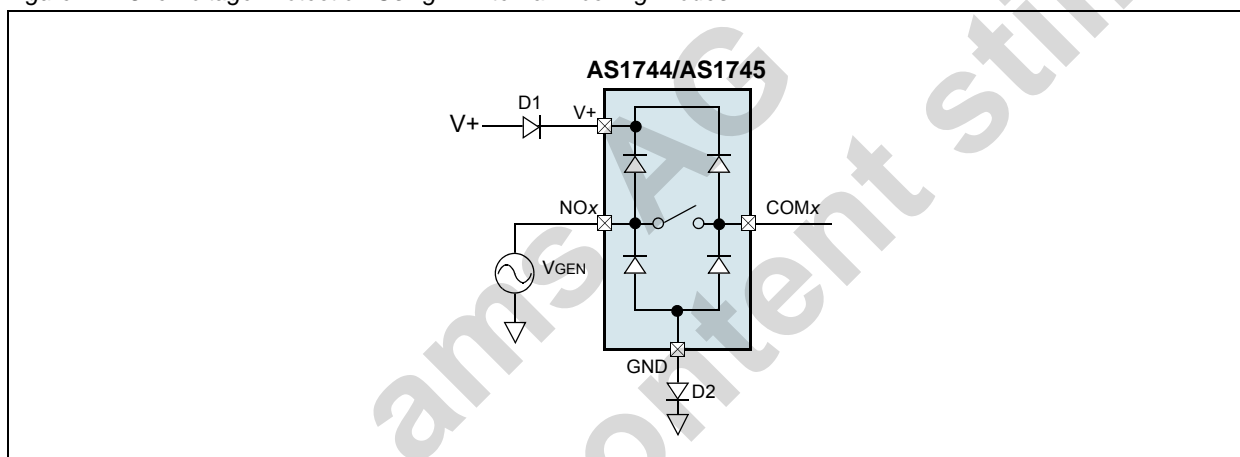
Always apply V+ before applying analog signals, especially if the analog signal is not current-limited. If the above sequence is not possible, and if the analog inputs are not current-limited to less than 30mA, add a small-signal diode as shown in [Figure 11](#) (D1). If the analog signal can dip below GND, add diode D2. Adding these diodes will reduce the analog range to a diode-drop (about 0.7V) below V+ (for D1), and a diode-drop above ground (for D2).

Note: Operation beyond the absolute maximum ratings (see page 3) may permanently damage the devices.

Overvoltage Protection

ON-resistance increases slightly at lower supply voltages.

Figure 11. Overvoltage Protection Using 2 External Blocking Diodes



Adding diode D2 to the circuit shown in [Figure 11](#) causes the logic threshold to be shifted relative to GND. Diodes D1 and D2 also protect against overvoltage conditions.

For example, in the circuit shown in [Figure 11](#), if the supply voltage goes below the absolute maximum rating, and if a fault voltage up to the absolute maximum rating is applied to an analog signal pin, no damage will result.

Note: The supply voltage (V+) must not exceed the absolute maximum rating of +7V.

Power Supply Bypass

Power supply connections to the devices must maintain a low impedance to ground. This can be done using a bypass capacitor, which will also improve noise margin and prevent switching noise propagation from the V+ supply to other components.

Layout Considerations

High-speed switches require proper layout and design procedures for optimum performance.

- Reduce stray inductance and capacitance by keeping traces short and wide.
- Ensure that bypass capacitors are as close to the device as possible.
- Use large ground planes where possible.

Timing Diagrams and Test Setups

Figure 12. Switching Time

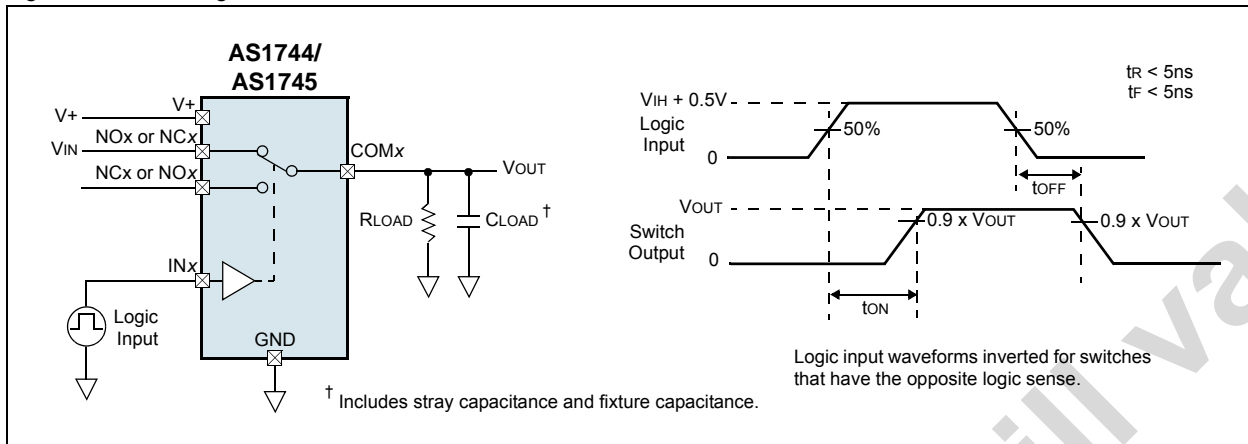


Figure 13. Break-Before-Make Interval

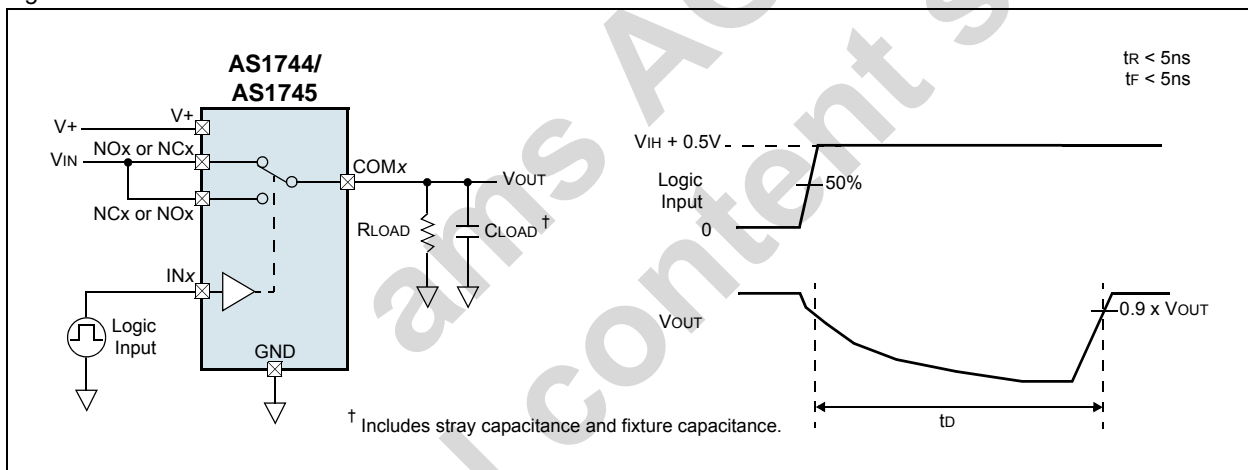


Figure 14. Charge Injection

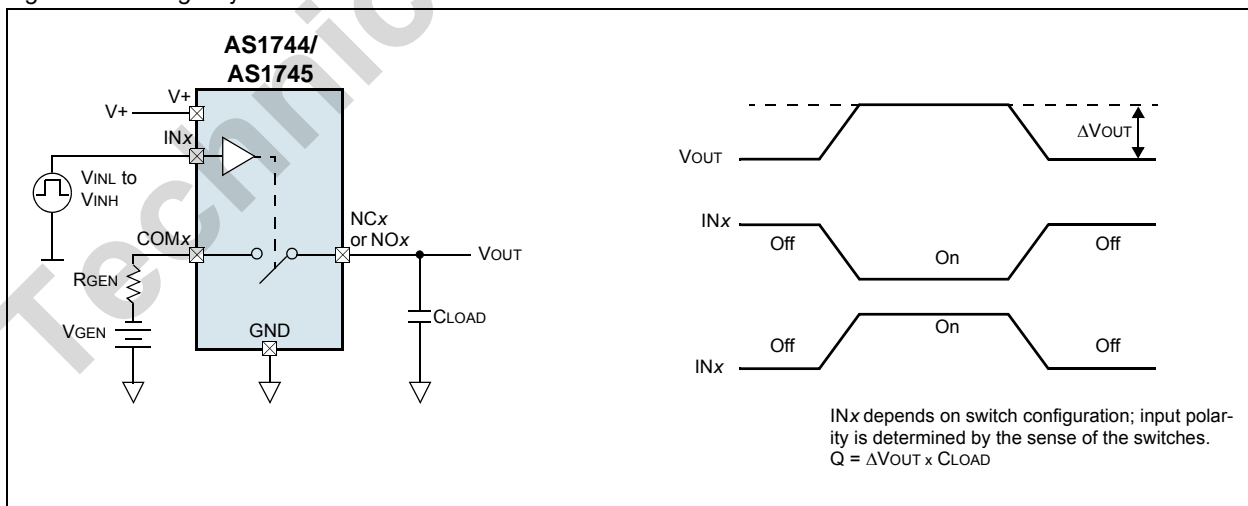


Figure 15. NO_x, NC_x, and COM_x Capacitance

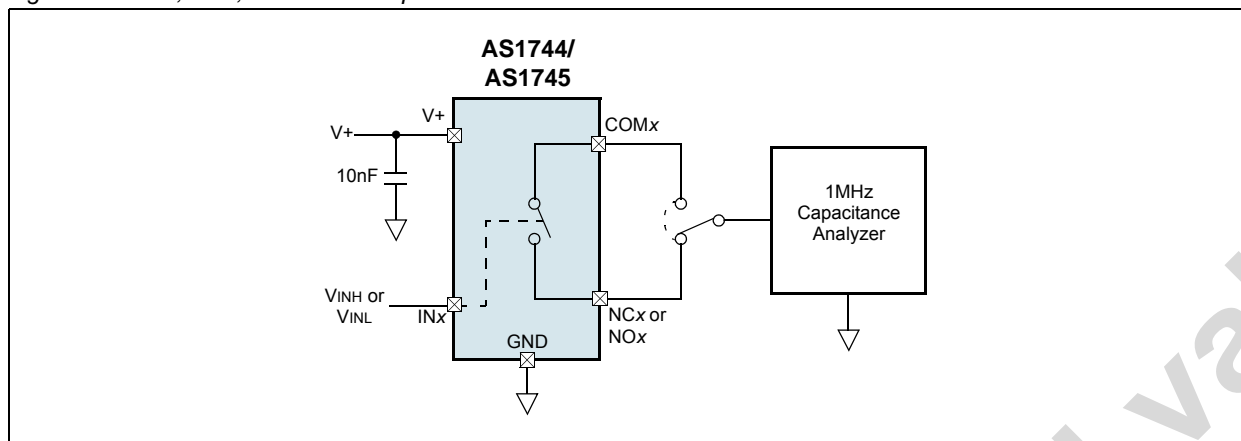
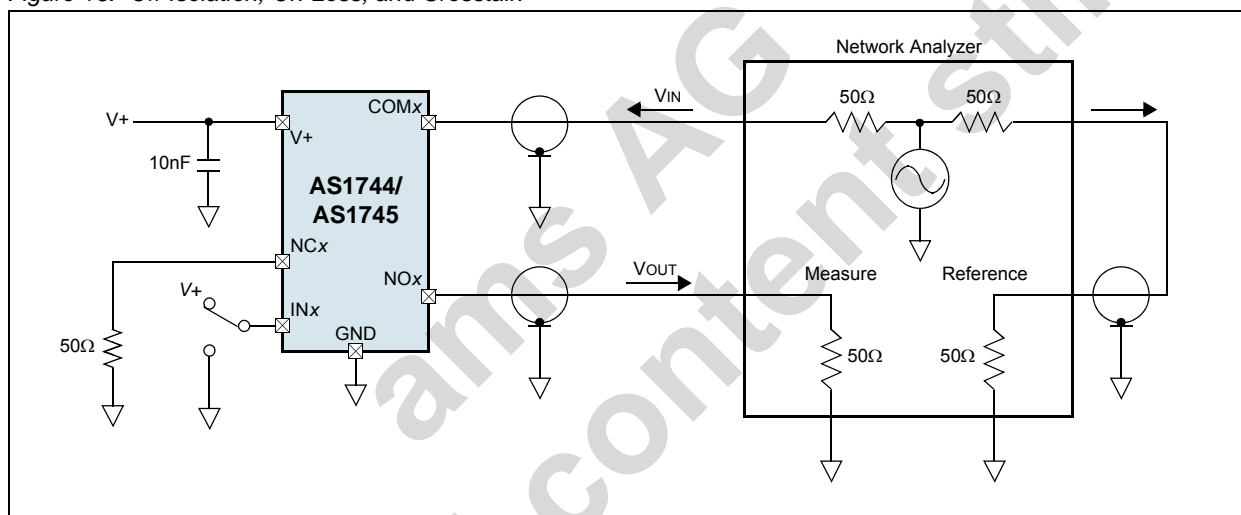


Figure 16. Off-Isolation, On-Loss, and Crosstalk



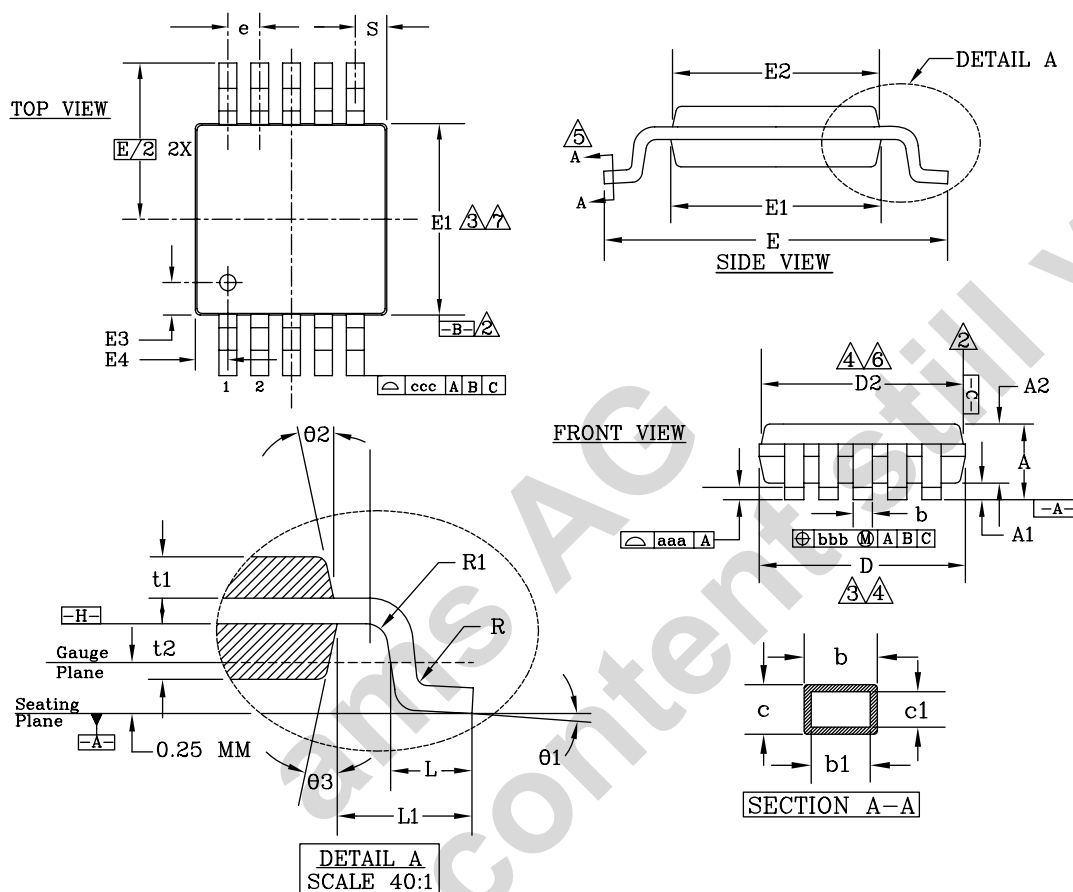
Notes:

1. Measurements are standardized against short-circuit at all terminals.
2. Off-isolation is measured between COM_x and the off NC_x/NO_x terminal of each switch. Off-isolation = $20\log(V_{OUT}/V_{IN})$.
3. Crosstalk is measured from one channel to all other channels.
4. Signal direction through the switch is reversed; worst values are recorded.

Package Drawings and Markings

The devices are available in a 10-pin MSOP package and a 10-pin TDFN package.

Figure 17. 10-pin MSOP Package



Symbol	Typ	±Tol	Symbol	Typ	±Tol
A	1.10	Max	b	0.23	+0.07/-0.08
A1	0.10	±0.05	b1	0.20	±0.05
A2	0.86	±0.08	c	0.18	±0.08
D	3.00	±0.10	c1	0.15	+0.03/-0.02
D2	2.95	±0.10	θ1	3.0°	±3.0°
E	4.90	±0.15	θ2	12.0°	±3.0°
E1	3.00	±0.10	θ3	12.0°	±3.0°
E2	2.95	±0.10	L	0.55	±0.15
E3	0.51	±0.13	L1	0.95BSC	-
E4	0.51	±0.13	aaa	0.10	-
R	0.15	+0.15/-0.08	bbb	0.08	-
R1	0.15	+0.15/-0.08	ccc	0.25	-
t1	0.31	±0.08	e	0.50 BSC	-
t2	0.41	±0.08	S	0.50 BSC	-

Notes:

1. All dimensions are in millimeters, angles in degrees, unless otherwise specified.
2. Datums B and C to be determined at datum plane H.
3. Dimensions D and E1 are to be determined at datum plane H.
4. Dimensions D2 and E2 are for top package; dimensions D and E1 are for bottom package.
5. Cross section A-A to be determined at 0.13 to 0.25mm from lead tip.
6. Dimensions D and D2 do not include mold flash, protrusion, or gate burrs.
7. Dimensions E1 and E2 do not include interlead flash or protrusion.

Figure 1: Dimensions and Nomenclature of the Test Vehicle

The figure illustrates the dimensions and nomenclature of the test vehicle, showing four views: Top View, Bottom View, Side View, and Detail B.

Top View: Shows the overall dimensions D (width) and E (height). The central INDEX AREA is defined as $(D/2 \times E/2)$. Dimensions $D/2$ and $E/2$ are indicated. A section line A-A is shown at the top, and B-B at the right.

Bottom View: Shows the underside of the vehicle. Dimensions $D2$ (width) and $E2$ (height) are indicated. It includes a PIN 1 MARKER, a hatched INDEX AREA $(D/2 \times E/2)$, and a row of pins. Dimensions N , $N-1$, and $(ND-1) \times e$ are shown. A section line B-B is shown at the bottom.

Side View: Shows the profile of the board. Dimensions A , $A1$, and $A3$ are indicated. It includes a SEATING PLANE and a row of pins.

Detail B: Shows a close-up of the pins. Dimensions $L1$, $L2$, and e are indicated. It includes a Datum A or B and a Terminal Tip.

Table 1: Dimensions

Symbol	Description	Value
D	Overall Width	100
E	Overall Height	100
$D/2$	Half Width	50
$E/2$	Half Height	50
$D2$	Width of Pin Array	100
$E2$	Height of Pin Array	100
N	Number of Pins	10
$N-1$	Number of Pins (excluding Pin 1)	9
$(ND-1) \times e$	Distance between pins	90
$L1$	Pin Length	10
$L2$	Pin Length	10
e	Pin Spacing	10

Table 2: Materials

Material	Symbol	Value
Substrate	ccc	C
Pin	ddd	C
Pin Plating	bbb	M
Pin Plating	aaa	C

Symbol	Min	Typ	Max	Notes
A	0.70	0.75	0.80	1, 2
A1	0.00	0.02	0.05	1, 2
A3		0.20 REF		1, 2
L1			0.15	1, 2
L2			0.13	1, 2
θ	0°		14°	1, 2
K	0.20			1, 2
K2	0.17			1, 2
b	0.18	0.25	0.30	1, 2, 5
e		0.5		
aaa		0.15		1, 2
bbb		0.10		1, 2
ccc		0.10		1, 2
ddd		0.05		1, 2
eee		0.08		1, 2
ggg		0.10		1, 2

Variations				
Symbol	Min	Typ	Max	Notes
D BSC		3.00		1, 2
E BSC		3.00		1, 2
D2	2.20		2.70	1, 2
E2	1.40		1.75	1, 2
L	0.30	0.40	0.50	1, 2
N		10		1, 2
ND		5		1, 2, 5

Notes:

1. Dimensioning and tolerancing are compliant with *ASME Y14.5M-1994*.
2. Dimensions are in millimeters, angles in degrees (°).
3. N is the total number of terminals.
4. The terminal 1 identifier and terminal numbering convention shall conform to *JESD 95-1 SPP-012*. Details of terminal 1 identifier are optional, but must be located within the zone indicated. The terminal 1 identifier may be either a mold, embedded metal or mark feature.
5. Dimension b applies to metallized terminal and is measured between 0.15 and 0.30mm from terminal tip.
6. ND refers to the maximum number of terminals on D side.
7. Variation shown in [Figure 18](#) is for illustration purposes only.
8. For variation identifier dimension details, refer to the Dimensions table.
9. For a complete set of dimensions for each variation, refer to the Variations table.
10. Unilateral coplanarity zone applies to the exposed heat sink slug and the terminals.
11. For a rectangular package, the terminal side of the package is determined by:
 - Type 1: Terminals are on the short side of the package.
 - Type 2: Terminals are on the long side of the package.
12. Variations specified as NJR (non JEDEC registered), with an additional dash number (e.g., -1, -2) are packages currently not registered with JEDEC.
13. When more than one variations exist for the same profile height, body size (DxE), and pitch, then those variations will be denoted by an additional dash number (i.e., -1,-2) for identification. The new variations shall be created based on any or all of the following factors: terminal count, terminal length, and exposed pad sizes.

10 Ordering Information

The devices are available as the standard products shown in [Table 5](#).

Table 5. Ordering Information

Type	Description	Delivery Form	Package
AS1744G	Dual SPDT Switch	Tube	10-pin MSOP
AS1744G-T	Dual SPDT Switch	Tape and Reel	10-pin MSOP
AS1744V-T [†]	Dual SPDT Switch	Tape and Reel	10-pin TDFN
AS1745G	Dual SPDT Switch	Tube	10-pin MSOP
AS1745G-T	Dual SPDT Switch	Tape and Reel	10-pin MSOP
AS1745V-T [†]	Dual SPDT Switch	Tape and Reel	10-pin TDFN

[†] Available upon request. Contact austriamicrosystems, AG for details.

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